

IN THE CLAIMS:

Please amend claims 1-14 as provided below:

1. (Currently amended) An Optoelectronic arrangement, comprising~~having~~:
 - [[-]] at least one emission component,
 - [[-]] a monitor component, which is operatively coupled~~assigned~~ to the emission component and detects at least some part of the~~the~~ radiation radiated by the emission component,
 - [[-]] a driver circuit electrically connected to the emission component and the monitor component, and
 - [[-]] a carrier substrate,
 - [[-]] the driver circuit being formed as a circuit integrated into the carrier substrate, and
 - [[-]] the monitor component likewise being integrated into the carrier substrate, and
 - [[-]] the emission component being formed as a separate structural part and being arranged on the carrier substrate.
2. (Currently amended) The Arrangement according to Claim 1, the monitor component being comprising a photodiode ~~whose~~ having a pn junction is integrated into the carrier substrate.
3. (Currently amended) The Arrangement according to Claim 1, the emission component ~~being formed as comprising~~ a vertically emitted laser component which is fixed above the monitor component on the carrier substrate, part of the laser light being radiated upward and part of the laser light being radiated downward onto the monitor component.

4. (Currently amended) The Arrangement according to Claim 3,
[[-]] the laser component ~~having~~comprising a laser substrate and a laser resonator,
[[-]] the laser resonator being arranged at ~~at~~that side of the laser component which is remote from the carrier substrate, and
[[-]] the laser substrate having, at ~~at~~the side facing the carrier substrate and in a manner adjoining the laser resonator, a cutout in such a way that downwardly radiated light falls onto the monitor component.
5. (Currently amended) The Arrangement according to Claim 3,
[[-]] the laser component ~~having~~comprising a laser substrate and a laser resonator,
[[-]] the laser resonator being arranged at ~~at~~that side of the laser component which faces the carrier substrate, and
[[-]] the laser substrate having, at ~~at~~the side remote from the carrier substrate and in a manner adjoining the laser resonator, a cutout ~~in such a way that facilitates radiating light is away from the carrier substrate~~coupled out upward.
6. (Currently amended) The Arrangement according to Claim 5, the laser component being arranged with ~~at~~the top side facing toward~~downward on~~ the carrier substrate and in this case having one or more~~both~~ electrical contacts located at the top side.
7. (Currently amended) The Arrangement according to Claim 1, the emission component being formed as a laser chip.
8. (Currently amended) The Arrangement according to Claim 1, the emission component being connected to the carrier substrate by at least one of adhesive bonding and wire bonding.

9. (Currently amended) The Arrangement according to Claim 1, the emission component being connected to the carrier substrate by flip-chip mounting.

10. (Currently amended) The Arrangement according to Claim 3, further comprising an array of vertically emitting laser components and respectively assigned monitor components ~~being provided, and, in the case of each laser component, wherein at least somepart of the laser light from the respective laser components is being radiated upward and somepart of the laser light is being radiated downward onto the associated monitor components.~~

11. (Currently amended) The Arrangement according to Claim 10,
[[-]] the array of vertically emitting laser components having a common laser substrate and ~~respectivea plurality of laser resonators for the laser components,~~
[[-]] the respective laser resonators ~~in each case~~ being arranged at respective ~~that~~ sides of the laser components ~~that~~ which faces the carrier substrate, and
[[-]] ~~respective~~ the laser substrates for the laser components ~~in each case~~ having, at the side remote from the carrier substrate and in a manner adjoining the laser resonators, respectivea ~~cutouts in such a way that~~ facilitate radiating light is away from the carrier substrate ~~coupled out upward.~~

12. (Currently amended) The Arrangement according to Claim 10, the laser components of the array being connected as redundant components.

13. (Currently amended) The Arrangement according to Claim 3, the carrier substrate being transparent to the radiated light.

14. (Currently amended) The Arrangement according to Claim 3, the emission component emitting light having a wavelength of between 650 and 850 nm.

15. (New) The arrangement according to Claim 14, wherein the emission component comprises GaAs.

16. (New) The arrangement according to Claim 1, wherein the emission component comprises a vertically emitting laser component (VCSEL).

17. (New) The arrangement according to Claim 1, wherein the driver circuit is integrated monolithically into the carrier substrate.

18. (New) The arrangement according to Claim 1, wherein the monitor component is integrated monolithically into the carrier substrate.

19. (New) The arrangement according to Claim 1, wherein the monitor component comprises a diode.

20. (New) The arrangement according to Claim 19, wherein the emission component comprises a laser chip, the diode being integrated monolithically into the carrier substrate and the laser chip being located on the carrier substrate above the diode.